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(71) Applicant: **TOKYO ELECTRON LIMITED** [JP/JP]; 3-1 Akasaka 5-chome, Minato-ku, Tokyo, 107-6325 (JP).

(71) Applicant (for JP only): **TOKYO ELECTRON U.S. HOLDINGS, INC.** [US/US]; 2400 Grove Boulevard, Austin, Texas 78741 (US).

(72) Inventors: **MALEEV, Ivan**; 2859 Bayview Dr., Fremont, California 94538 (US). **BHADURI, Basanta**; 2859 Bayview Dr., Fremont, California 94538 (US). **TUITJE, Holger**; 2859 Bayview Dr., Fremont, California 94538 (US). **TIAN, Xinkang**; 2859 Bayview Dr., Fremont, Cal-

ifornia 94538 (US). **SONG, Da**; 2859 Bayview Dr., Fremont, California 94538 (US).

(74) Agent: **STRANG, Eric**; Tokyo Electron U.S. Holdings, Inc., 2400 Grove Boulevard, Austin, Texas 78741 (US).

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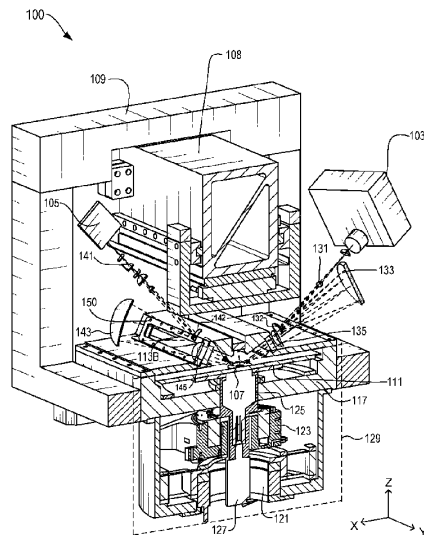


Figure 1B

(57) Abstract: A system includes a vacuum chamber having a wafer chuck therein and side windows slanted relative to the wafer chuck. A wafer stage is positioned below the wafer chuck and configured to rotate the wafer chuck and move the wafer chuck vertically. Illumination optics, including an illumination corrector lens, are configured to receive light and direct the light through an illumination vacuum window of the side windows to an optical spot on the wafer. Collection optics, including a collection corrector lens, are configured to receive the light from the optical spot through a collection vacuum window of the side windows and direct the light to a detector. A transfer module is configured to move the illumination optics and the collection optics parallel to the illumination vacuum window and the collection vacuum window respectively. The illumination corrector lens and the collection corrector lens are configured to reduce chromatic aberration.

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